



Corres. and Mail
BOX AF

2813

**RESPONSE UNDER 37 CFR 1.116
EXPEDITED PROCEDURE
EXAMINING GROUP 2813**

IR-1881 (2-2532)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Bharat Shivkumar, et al.

Date: April 26, 2005

Serial No.: 09/812,027

Group Art Unit: 2813

Filed: March 19, 2001

Examiner: James M. Mitchell

For: SEMICONDUCTOR MULTICHIP MODULE PACKAGE WITH IMPROVED
THERMAL PERFORMANCE; REDUCED SIZE AND IMPROVED MOISTURE
RESISTANCE

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

*OK to enter
5/29/05*

AMENDMENT/SUBMISSION

Sir: *JMM*

This is a response to the Office Action mailed January 27, 2005 in the above-identified application. Reconsideration of the application is respectfully requested.

FEE CALCULATION

Any additional fee required has been calculated as follows:

_____ If checked, "Small Entity" status is claimed.

	NO. CLAIMS AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR		EXTRA PRESENT		RATE	ADDIT. FEE
TOTAL	8	MINUS	20	* =	0	X	(\$25 SE or \$50)	\$-0-
INDEP.	2	MINUS	4	** =	0	X	(\$100 SE or \$200)	\$-0-
FIRST PRESENTATION OF MULTIPLE DEPENDENT CLAIM						X	(\$180 SE or \$360)	\$-0-

* not less than 20 ** not less than 3

TOTAL \$-0-